

GOLD ALLOY WIRE FOR BALL BONDING

ABSTRACT

To provide Au alloy wire for ball bonding, which is superior wire strength, and also is superior at formability of molten ball and roundness of compressed ball, moreover is superior at stitch bondability; is available for high density wiring of semiconductor devices.

Au alloy wire for ball bonding comprising: 15 – 50 mass ppm Mg, 10 – 30 mass ppm Ca, 5 – 20 mass ppm Eu, 5 – 20 mass ppm Y, 5 – 20 mass ppm La and residual Au is more than 99.998 mass % purity, moreover, purity of more than 99.98 mass % Au, mass of additive Ca is less than the value of total amount of additive Eu and additive La, and mass of additive Y is less than the value of total amount of additive Ca and additive Eu, and mass of 20 – 40 mass ppm Mg.

[Representative Figure]
Fig. 1.